

# ZXMHC6A07T8

## COMPLEMENTARY 60V ENHANCEMENT MODE MOSFET H-BRIDGE

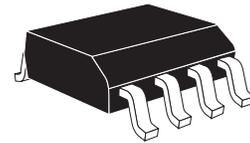
### SUMMARY

N-Channel  $V_{(BR)DSS} = 60V$ ;  $R_{DS(ON)} = 0.300\Omega$ ;  $I_D = 1.8A$

P-Channel  $V_{(BR)DSS} = -60V$ ;  $R_{DS(ON)} = 0.425\Omega$ ;  $I_D = -1.5A$

### DESCRIPTION

This new generation of trench MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



### FEATURES

- Low On - Resistance
- Fast switching speed
- Low threshold
- Low gate drive
- Low profile SOIC package

### APPLICATIONS

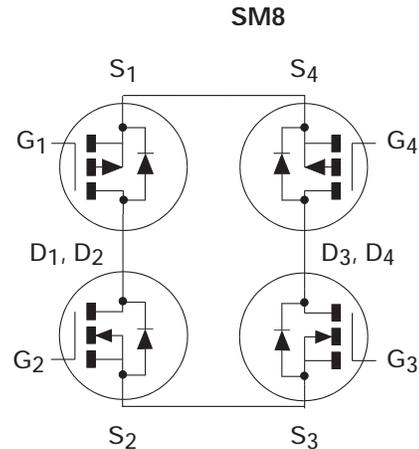
- Motor Drive

### ORDERING INFORMATION

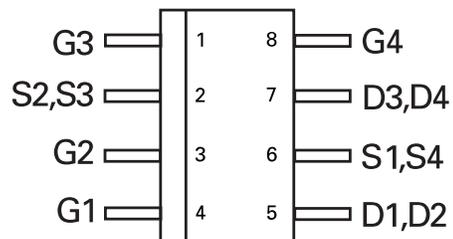
DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXMHC6A07T8TA	7"	12mm	1000 units
ZXMHC6A07T8TC	13"	12mm	4000 units

### DEVICE MARKING

- ZXMH  
C6A07



### PINOUT DIAGRAM



Top View

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## ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	N-Channel	P-Channel	UNIT
Drain-Source Voltage	$V_{DSS}$	60	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current @ $V_{GS}=10V$ ; $T_A=25^\circ C$ (b)(d) @ $V_{GS}=10V$ ; $T_A=70^\circ C$ (b)(d) @ $V_{GS}=10V$ ; $T_A=25^\circ C$ (a)(d)	$I_D$	1.8	-1.5	A
		1.4	-1.2	A
		1.6	-1.3	A
Pulsed Drain Current (c)	$I_{DM}$	8.7	-7.5	A
Continuous Source Current (Body Diode) (b)	$I_S$	2.3	-2.1	A
Pulsed Source Current (Body Diode) (c)	$I_{SM}$	8.7	-7.5	A
Power Dissipation at $T_A=25^\circ C$ (a)(d)	$P_D$	1.3		W
Linear Derating Factor		10.4		mW/ $^\circ C$
Power Dissipation at $T_A=25^\circ C$ (b)(d)	$P_D$	1.7		W
Linear Derating Factor		13.6		mW/ $^\circ C$
Operating and Storage Temperature Range	$T_j:T_{stg}$	-55 to +150		$^\circ C$

## THERMAL RESISTANCE

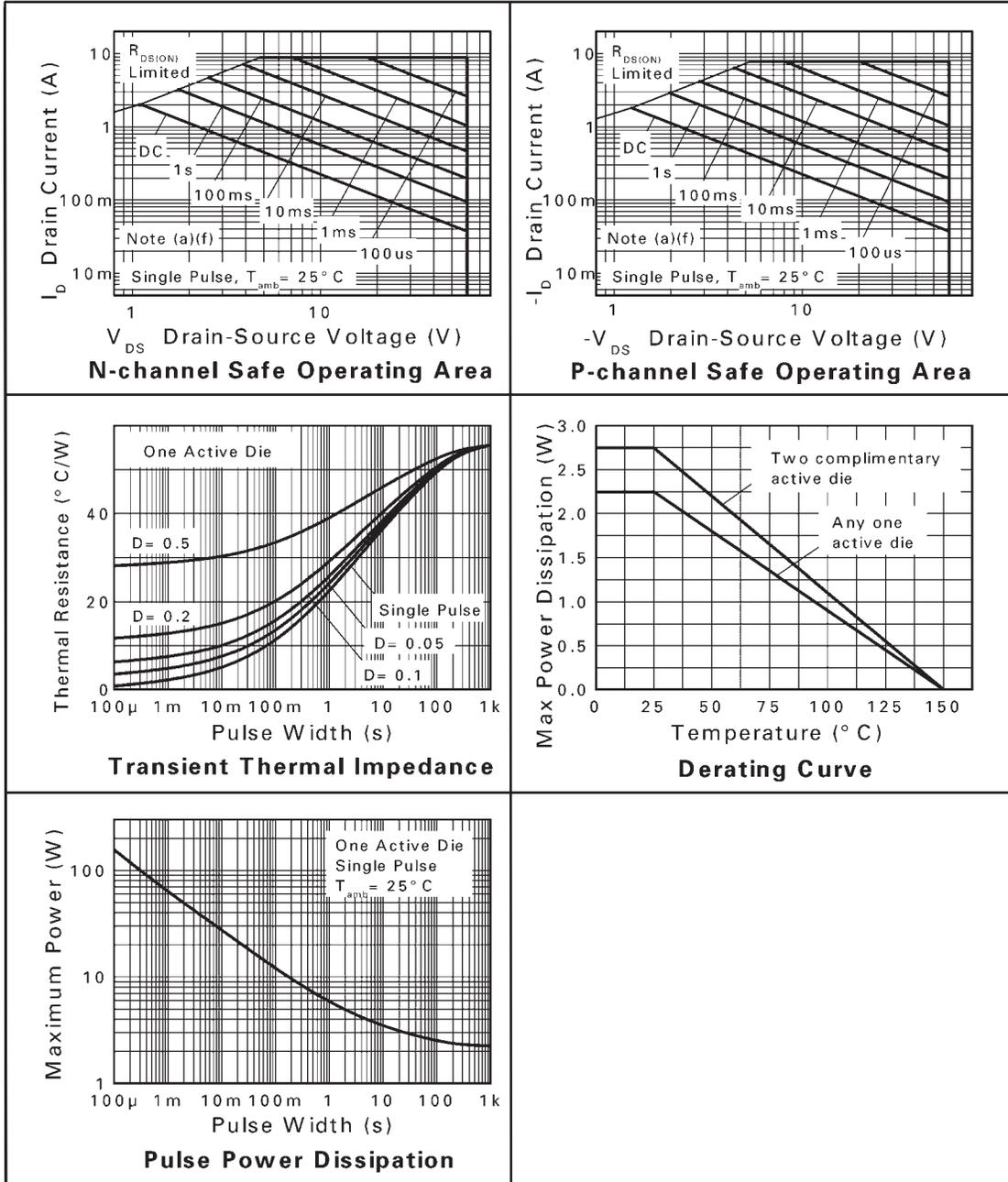
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)(d)	$R_{\theta JA}$	96	$^\circ C/W$
Junction to Ambient (b)(d)	$R_{\theta JA}$	73	$^\circ C/W$

### Notes

- (a) For a device surface mounted on 50mm x 50mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions.
- (b) For a device surface mounted on FR4 PCB measured 1.6mm at  $t \leq 10$ sec.
- (c) Repetitive rating - 50mm x 50mm x 1.6mm FR4 PCB,  $D = 0.2$ , pulse width 300 $\mu$ S pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.
- (d) For device with one active die.

# ZXMHC6A07T8

## TYPICAL CHARACTERISTICS



# ZXMHC6A07T8

## N-CHANNEL

ELECTRICAL CHARACTERISTICS (at  $T_{amb} = 25^{\circ}\text{C}$  unless otherwise stated).

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	60			V	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$
Zero Gate Voltage Drain Current	$I_{DSS}$			1	$\mu\text{A}$	$V_{DS}=60\text{V}, V_{GS}=0\text{V}$
Gate-Body Leakage	$I_{GSS}$			100	nA	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	1		3.0	V	$I_D=250\mu\text{A}, V_{DS}=V_{GS}$
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.300 0.450	$\Omega$ $\Omega$	$V_{GS}=10\text{V}, I_D=1.8\text{A}$ $V_{GS}=4.5\text{V}, I_D=1.3\text{A}$
Forward Transconductance (1)(3)	$g_{fs}$		2.3		S	$V_{DS}=15\text{V}, I_D=1.8\text{A}$
<b>DYNAMIC (3)</b>						
Input Capacitance	$C_{iss}$		166		pF	$V_{DS}=40\text{V}, V_{GS}=0\text{V},$ $f=1\text{MHz}$
Output Capacitance	$C_{oss}$		19.5		pF	
Reverse Transfer Capacitance	$C_{rss}$		8.7		pF	
<b>SWITCHING (2) (3)</b>						
Turn-On Delay Time	$t_{d(on)}$		1.8		ns	$V_{DD}=30\text{V}, I_D=1.8\text{A}$ $R_G=6.0\Omega, V_{GS}=10\text{V}$
Rise Time	$t_r$		1.4		ns	
Turn-Off Delay Time	$t_{d(off)}$		4.9		ns	
Fall Time	$t_f$		2.0		ns	
Gate Charge	$Q_g$		1.65		nC	$V_{DS}=30\text{V}, V_{GS}=5\text{V},$ $I_D=1.8\text{A}$
Total Gate Charge	$Q_g$		3.2		nC	$V_{DS}=30\text{V}, V_{GS}=10\text{V},$ $I_D=1.8\text{A}$
Gate-Source Charge	$Q_{gs}$		0.67		nC	
Gate-Drain Charge	$Q_{gd}$		0.82		nC	
<b>SOURCE-DRAIN DIODE</b>						
Diode Forward Voltage (1)	$V_{SD}$		0.85	0.95	V	$T_J=25^{\circ}\text{C}, I_S=0.45\text{A},$ $V_{GS}=0\text{V}$
Reverse Recovery Time (3)	$t_{rr}$		20.5		ns	$T_J=25^{\circ}\text{C}, I_F=1.8\text{A},$ $di/dt=100\text{A}/\mu\text{s}$
Reverse Recovery Charge (3)	$Q_{rr}$		21.3		nC	

### NOTES

- (1) Measured under pulsed conditions. Width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .  
 (2) Switching characteristics are independent of operating junction temperature.  
 (3) For design aid only, not subject to production testing.

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## P-CHANNEL

ELECTRICAL CHARACTERISTICS (at  $T_{amb} = 25^{\circ}\text{C}$  unless otherwise stated).

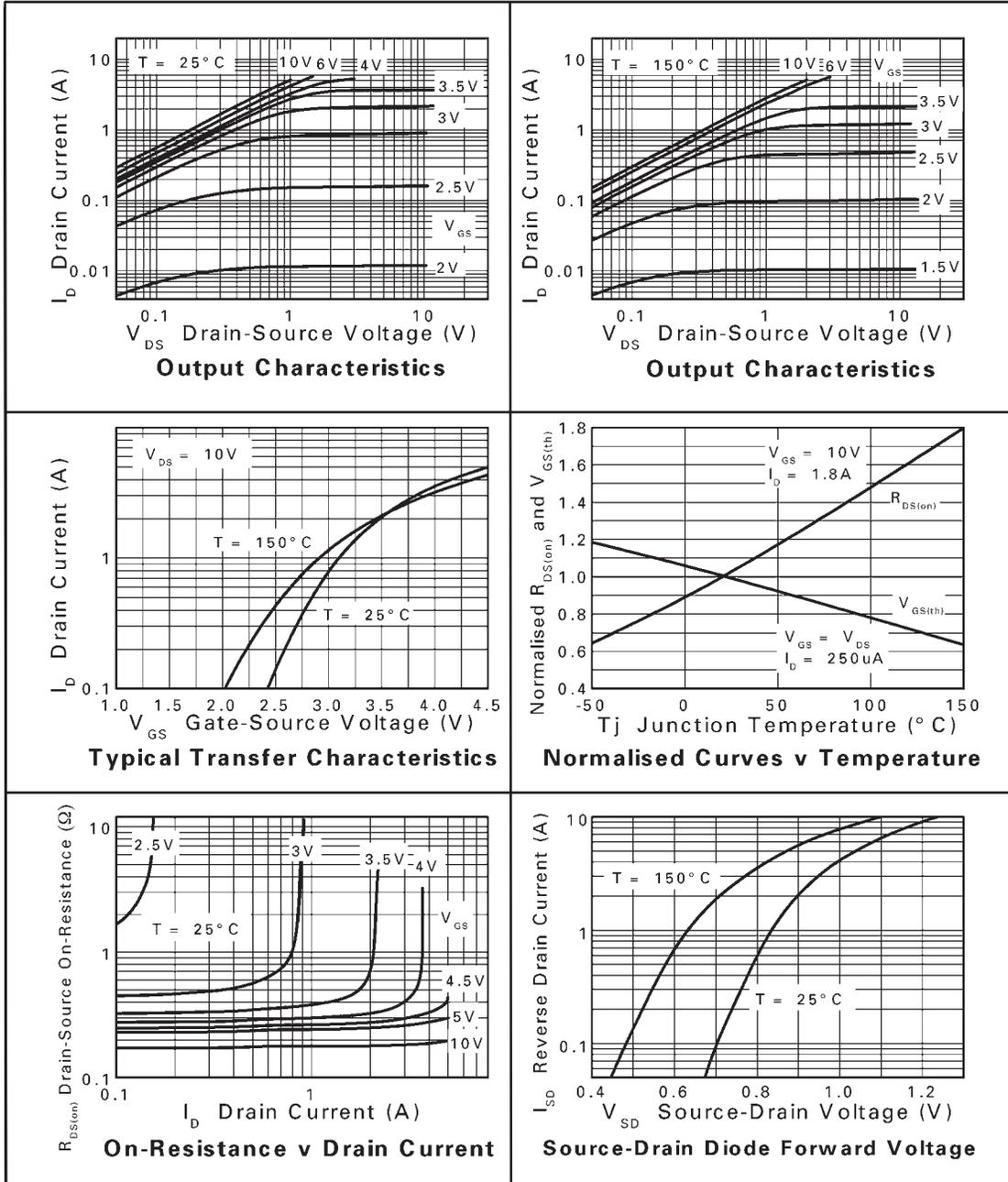
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	-60			V	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$
Zero Gate Voltage Drain Current	$I_{DSS}$			-1	$\mu\text{A}$	$V_{DS} = -60\text{V}, V_{GS} = 0\text{V}$
Gate-Body Leakage	$I_{GSS}$			100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	-1.0			V	$I_D = -250\mu\text{A}, V_{DS} = V_{GS}$
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.425 0.630	$\Omega$ $\Omega$	$V_{GS} = -10\text{V}, I_D = -0.9\text{A}$ $V_{GS} = -4.5\text{V}, I_D = -0.8\text{A}$
Forward Transconductance (1)(3)	$g_{fs}$		1.8		S	$V_{DS} = -15\text{V}, I_D = -0.9\text{A}$
<b>DYNAMIC (3)</b>						
Input Capacitance	$C_{iss}$		233		pF	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Output Capacitance	$C_{oss}$		17.4		pF	
Reverse Transfer Capacitance	$C_{rss}$		9.6		pF	
<b>SWITCHING(2) (3)</b>						
Turn-On Delay Time	$t_{d(on)}$		1.3		ns	$V_{DD} = -30\text{V}, I_D = -1\text{A}$ $R_G = 6.0\Omega, V_{GS} = -10\text{V}$
Rise Time	$t_r$		21.3		ns	
Turn-Off Delay Time	$t_{d(off)}$		5.3		ns	
Fall Time	$t_f$		11.6		ns	
Gate Charge	$Q_g$		2.4		nC	$V_{DS} = -30\text{V}, V_{GS} = -5\text{V}, I_D = -0.9\text{A}$
Total Gate Charge	$Q_g$		5.1		nC	$V_{DS} = -30\text{V}, V_{GS} = -10\text{V}, I_D = -0.9\text{A}$
Gate-Source Charge	$Q_{gs}$		0.7		nC	
Gate-Drain Charge	$Q_{gd}$		0.7		nC	
<b>SOURCE-DRAIN DIODE</b>						
Diode Forward Voltage (1)	$V_{SD}$		-0.85	-0.95	V	$T_J = 25^{\circ}\text{C}, I_S = -0.8\text{A}, V_{GS} = 0\text{V}$
Reverse Recovery Time (3)	$t_{rr}$		22.6		ns	$T_J = 25^{\circ}\text{C}, I_F = -0.9\text{A}, di/dt = 100\text{A}/\mu\text{s}$
Reverse Recovery Charge (3)	$Q_{rr}$		23.2		nC	

### NOTES

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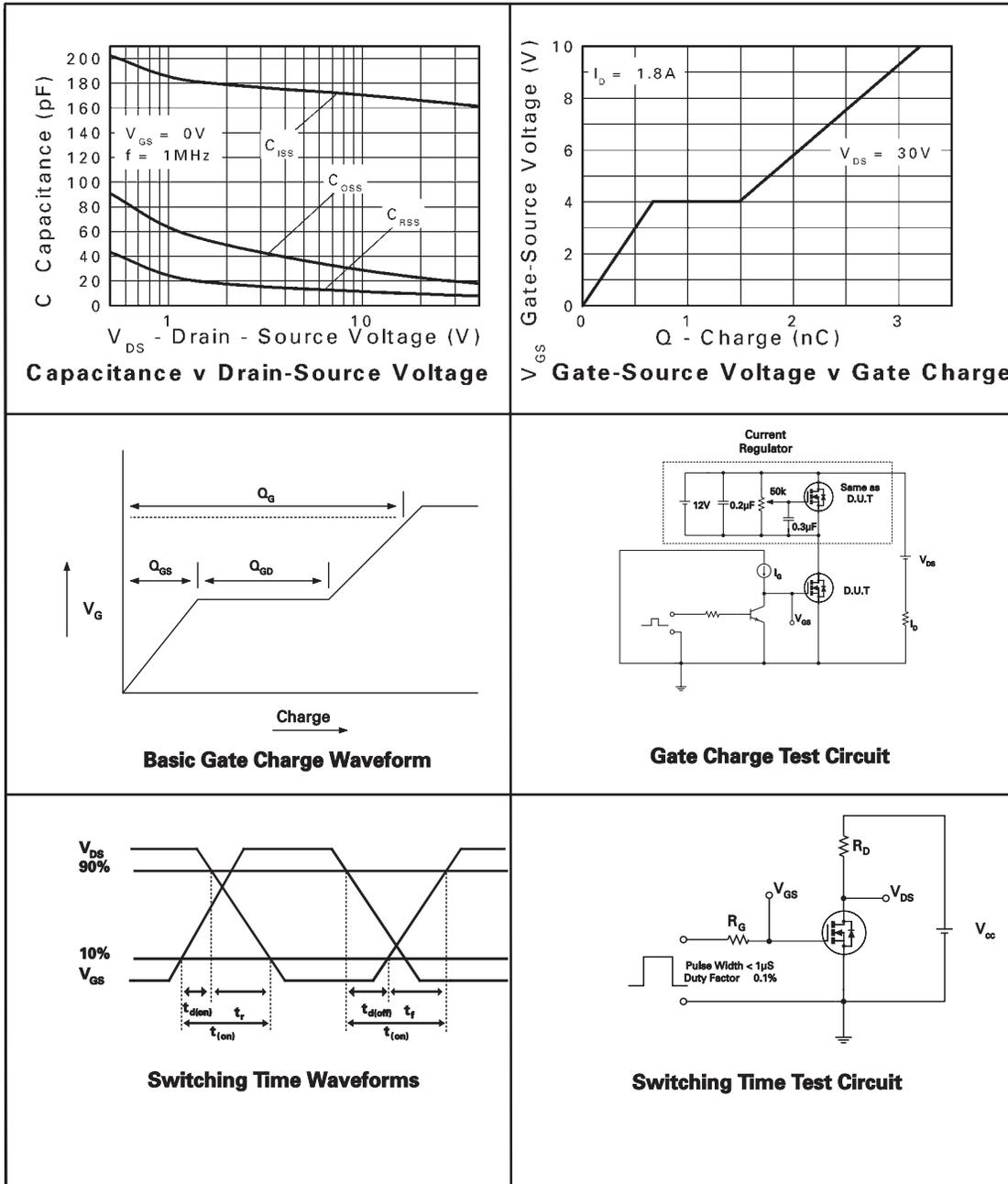
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## N-CHANNEL TYPICAL CHARACTERISTICS



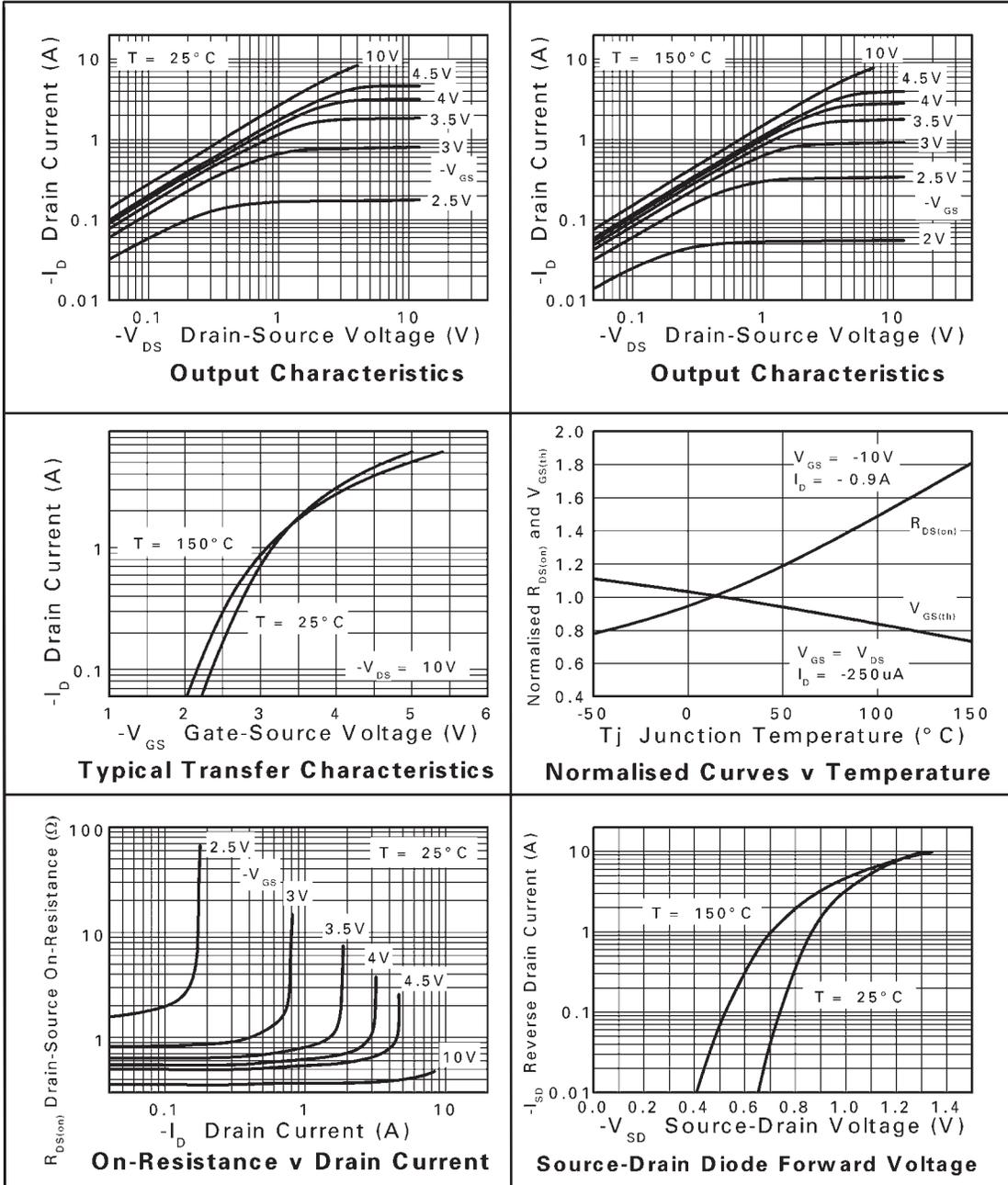
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## N-CHANNEL TYPICAL CHARACTERISTICS



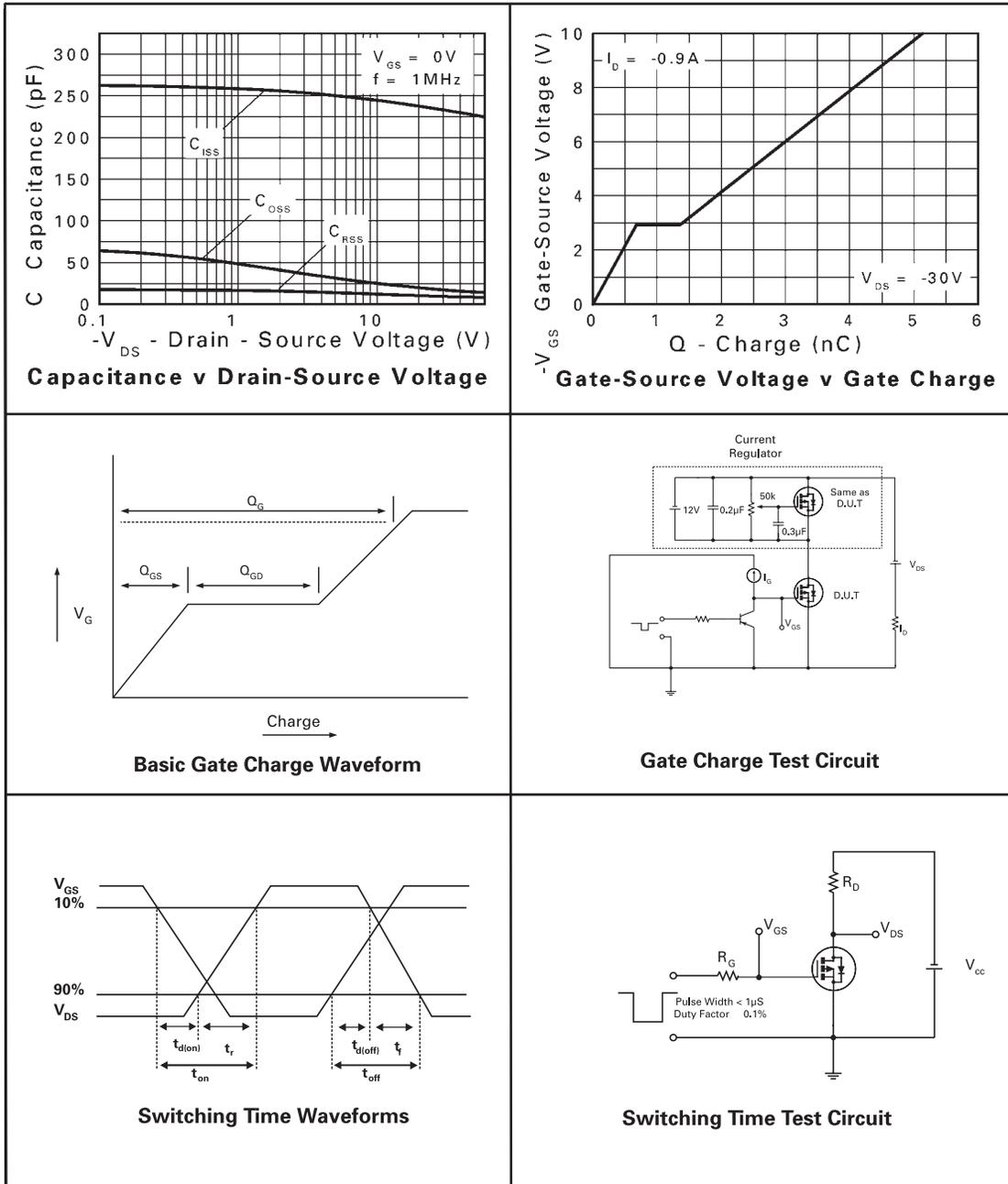
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## P-CHANNEL TYPICAL CHARACTERISTICS

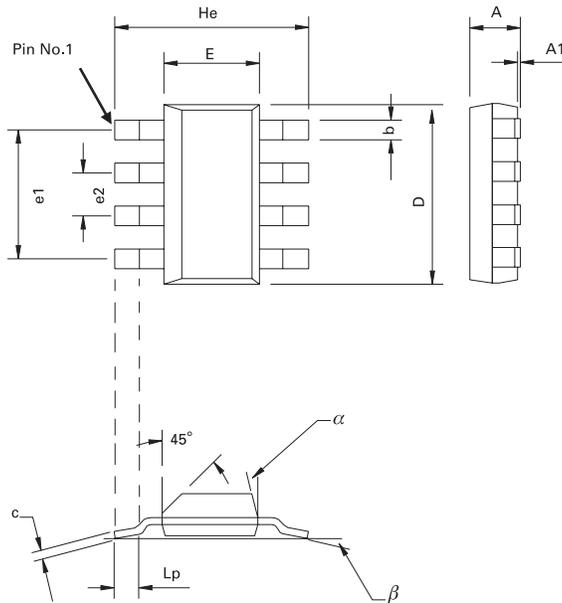


# ZXMHC6A07T8

## P-CHANNEL TYPICAL CHARACTERISTICS



# ZXMHC6A07T8



DIM	Millimetres			Inches		
	MIN	TYP	MAX	MIN	TYP	MAX
A	-	-	1.7	-	-	0.067
A1	0.02	-	0.1	0.0008	-	0.004
b	-	0.7	-	-	0.028	-
c	0.24	-	0.32	0.009	-	0.013
D	6.3	-	6.7	0.248	-	0.264
E	3.3	-	3.7	0.130	-	0.145
e1	-	4.59	-	-	0.180	-
e2	-	1.53	-	-	0.060	-
He	6.7	-	7.3	0.264	-	0.287
Lp	0.9	-	-	0.035	-	-
α	-	-	15°	-	-	15°
β	-	10°	-	-	10°	-

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